TO

COUNT	DESCRIPTION	ONS BY CHKD DA			DATE	COUNT		DESCRIPTION OF REVISIONS		BY CHKD		DAT	DATE	
					+		M							
APPLICA	L ABLE STAI	NDARD							I		L	l		
7 11 1 2107	OPERATIN	OPERATING TEMPERATURE RANGE		TO +	 -85 '	°C(NO	TE1)	STOR	AGE ERATURE RANGE	-10°C 7	ΓΟ +	60°C(I	TON	E2)
RATING	3	VOLTAGE							RRENT 3 A					
	VOLIA	GL	SPECIFICATIONS											
TO USE MENTO											ОТ	AT		
	TEM		TEST WIETHOD							REGUITENTO				7.1
	RUCTION EXAMINATION	N VISUALI	VISUALLY AND BY MEASURING INSTRUMENT.							DRAWING.			×	×
MARKING			CONFIRMED VISUALLY.										×	×
	IC CHAR	ACTERIS	TERISTICS										<u> </u>	
1			100 mA (DC OR 1000 Hz).							30 mΩ MAX.				_
INSULATION RESISTANCE		500 V DC	500 V DC.							1000MΩ MIN.				
VOLTAGE PROOF		650V AC	650V AC FOR 1 min.							NO FLASHOVER OR BREAKDOWN.				_
MECHA	NICAL CH	ARACTE	RISTIC	S										
MECHANICAL OPERATION			30 TIMES INSERTIONS AND EXTRACTIONS.							 CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				_
VIBRATION	١		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.							① NO ELECTRICAL DISCONTINUITY OF 1µs.				_
sноск		490 m/s ²	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.							, CRACK OR	LOOS	SENESS	×	
ENVIRO	NMENTA				S				OF PARTS.					L
RAPID CHANGE OF TEMPERATURE		TEMPER TIME	TEMPERATURE -55→ 5~35 →+85→ 5~35 °C						 CONTACT RESISTANCE: 30 mΩ MAX. INSULATION RESISTANCE: 1000 MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				×	_
DAMP HEAT (STEADY STATE)		EXPOSE	EXPOSED AT 40 ± 2 °C, 90 ∼ 95 %, 96 h.						 CONTACT RESISTANCE: 30 mΩ MAX. INSULATION RESISTANCE: 1000 MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				×	
RESISTAN SOLDERIN		I	SOLDER TEMPERATURE, 250±5°C, FOR. IMMERSION, DURATION, 10 s.						NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.					_
SOLDERABILITY		l l	SOLDERED AT SOLDER TEMPERATURE, 230±5 °C FOR INSERTION DURATION, 5 s.							SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				
REMARK						[DRAWN	DESIGNED	CHECKED	APF	ROVED	RELE	ASED	
NOTE2:APP UNU BOA APPI	LY TO THE SED PRODUC RD,OPERATING LIED FOR INTE	CONDITION C TS BEFORE TEMPERAT RIM STORAGE	ERATURE RISE BY CURRENT. NDITION OF LONG TERM STORAGE FO BEFORE PCB ON BOARD, AFTER PC TEMPERATURE AND HUMIDITY RANGE I STORAGE DURING TRANSPORTATION. Ified, refer to JIS C 5402.				IS M.N	Nakam	101 01.1	J. Qna 04.04.16	J.	Oma 04,16		
Note QT:	Note QT:Qualification Test AT:Assurance Test X:Applicable Test													
HS.	HIROSE ELECTRIC CO., LTD. SPECIFICATION SHEET PART NO. DF1-*P-2. 5DSA (05)													
CODE NO.(OLD) DRAWING NO. PART NO. C L 5 4 1										1/1				

(NC)